PCN Number:	201	.90703000		PCN Da		te: Aug.		20, 2019	
Title: Datasheet for DS250DF810									
<b>Customer Contact:</b>	PCN Manager					Dept:		Quality Services	
Proposed 1 <sup>st</sup> Ship Da									
Change Type:									
Assembly Site			Design			Wafer Bump Site			
Assembly Process		$\boxtimes$	Data Sheet				Wafer Bump Material		
Assembly Materials			Part number change				Wafer Bump Process		
Mechanical Specification			Test Site			Wafer Fab Site			
Packing/Shipping/Labeling		ing	Test Process			Щ		r Fab Materials	
						Wafe	r Fab Process		
Notification Details									
Description of Change:									
Texas Instruments Incorporated is announcing a change.									
The product datasheet(s) is being updated as summarized below.									
TEYAS									
TEXAS INSTRUMENTS DS250DF810								DS250DF810	
					SNL	S513B	-DECEMBI	ER 2015-REVISED JUNE 2019	
Changes from Revision A (February 2019) to Revision B									
Changed Operating junction temperature from -10 to -40									
Changed Supported Data Rates table									
The datasheet number will be changing.									
Device Family			Change From:				Change To:		
DS250DF810			SNLS513A				SNLS513B		
The revised version of the datasheet is not available on the TI website. Please contact the TI Customer Quality Engineer (CQE) for a copy of the datasheet.									
Reason for Change:									
To accurately reflect device characteristics.									
Change Min Operation junction and ambient temperature from -10 C to -40 C									
Change Supported data rates range MIN from 20.6 Gbps to 20.2752 Gbps									
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):									
Electrical specification performance changes as indicated above.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
DS250DF800ABVR	DS	S250DF800	ABVT	DS250DF	810A	BVR		DS250DF810ABVT	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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